

AMENDMENTS TO THE SPECIFICATION

Please amend the paragraph on page 1, lines 4 to 6, as follows:

This is a Continuation Application of U.S. Application No. ~~10/031,000~~ 10/031,000, filed January 16, 2002, which is the National Stage of International Application No. PCT/JP00/04699, July 13, 2000.

Please amend the paragraph on page 36, line 26 to page 37, line 1, as follows:

Next, in step 203 shown in Fig. 25 and Fig. 36, the first thermoplastic resin base material 422 on which the semiconductor device 414 provided with the bumps 413 is mounted is held between hot pressing plates 471 and 472, and the semiconductor device 414 provided with the bumps 413 and the first thermoplastic resin base material 422 are pressurized ~~relatively~~ relative to each other by a semiconductor part pressurizing device 473 with heat applied to them, inserting the semiconductor device 414 into the first thermoplastic resin base material 422. When a first thermoplastic resin base material made of, for example, polyethylene terephthalate is employed, the hot pressing conditions include a pressure of 30 105 Pa, a temperature of 120 C, and a pressing time of one minute. The temperature and the pressure are varied according to the material of the first thermoplastic resin base material 422.

Please amend the paragraph on page 38, lines 7 to 17 as follows:

That is, for example, a cylindrical structure that internally has a hollow portion 451 is employed as the extension portion-forming member 450. By heating the extension portion-forming member 450 to a temperature of, for example, 200 C by means of a heating

device 453 connected to the extension portion-forming member 450 and pressurizing the tip 452 of the extension portion-forming members 450 against the member forming surfaces 415 with a load of 100g per bump by means of the extension portion-forming member-use pressurizing device 454, the member forming surfaces 415 are deformed, and parts of the bumps 413 enter a hollow portion ~~450a~~ 451. Therefore, after the pressurization, rectangularly projecting portions 418 projecting from the member forming surfaces 415 are formed integrally with the bumps 413 on the member forming surfaces 415.